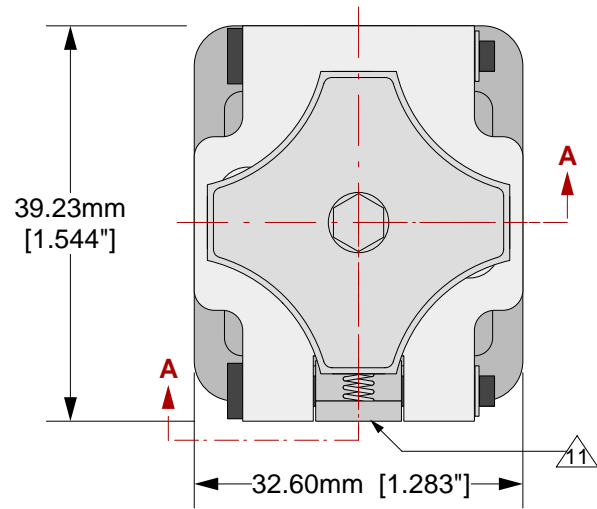
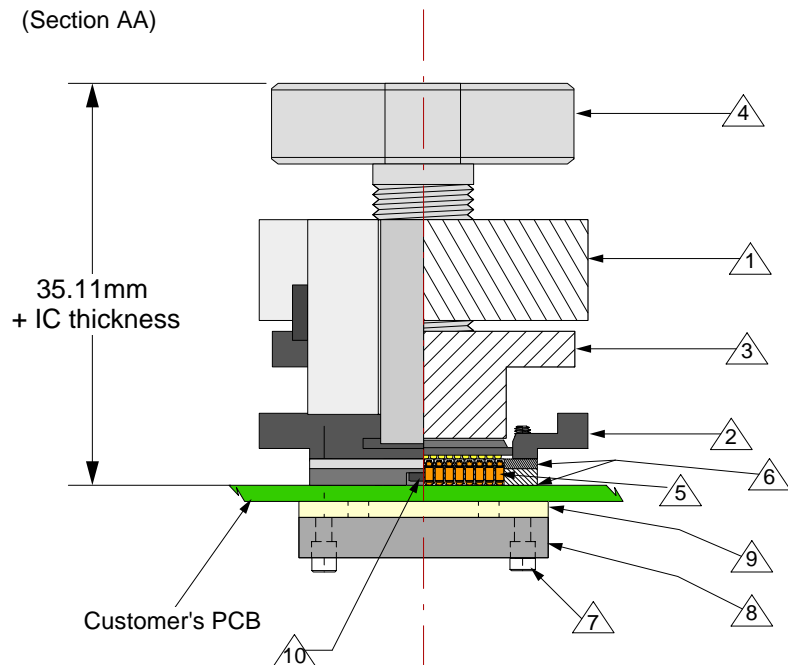


Top View



Side View
(Section AA)




Features

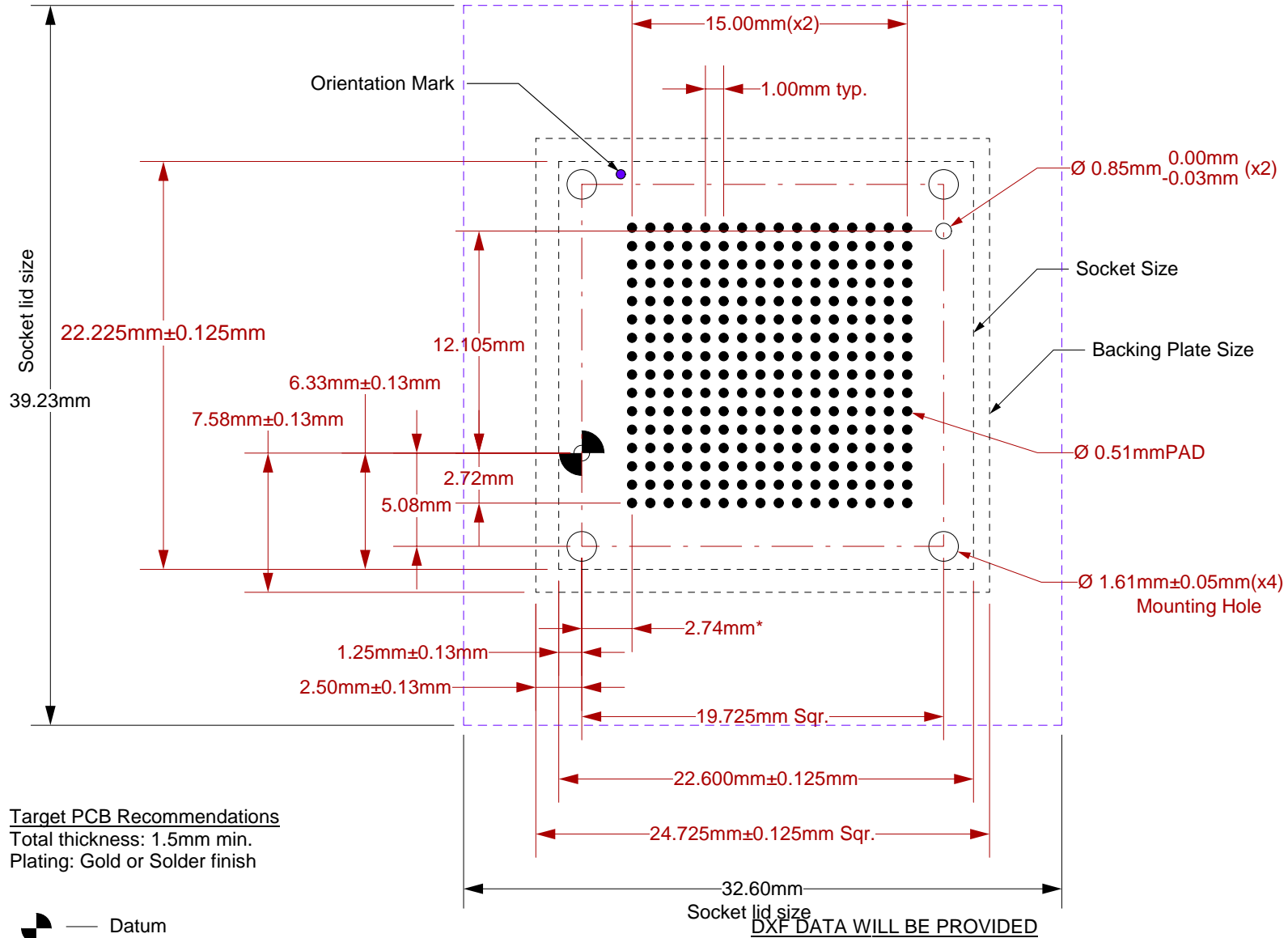
- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

- 1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 18 mm.
- 2 Socket Base: Black anodized 7075 Aluminum. Height = 4.5 mm.
- 3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 9.5 mm.
- 4 Compression Screw: Clear anodized 7075 Aluminum. Height = 23 mm, Fluted Knob
- 5 Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ultem 1000.
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized 7075 Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized 7075 Aluminum.

 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	SS-BGA256E-01 Drawing	Status: Released	Scale: 1.25:1	Rev: C
	Drawing: J. Glab	Date: 2/16/07		
	File: SS-BGA256E-01 Dwg	Modified: 12/20/07		

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.



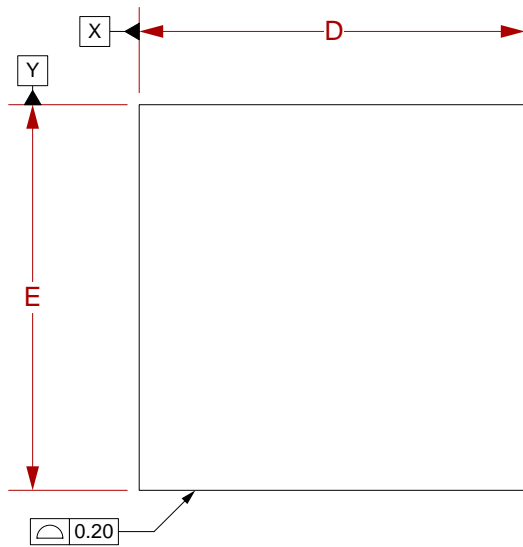
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

Datum

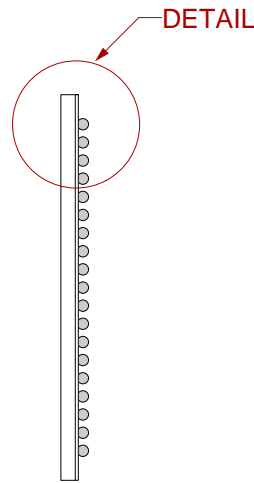
	SS-BGA256E-01 Drawing			Status: Released	Scale: 3:1	Rev: C
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com			Drawing: J . Glab		Date: 2/16/07
				File: SS-BGA256E-01 Dwg		Modified: 12/20/07

Recommended PCB Layout
Tolerances: ±0.025mm [±0.001"]
unless stated otherwise.

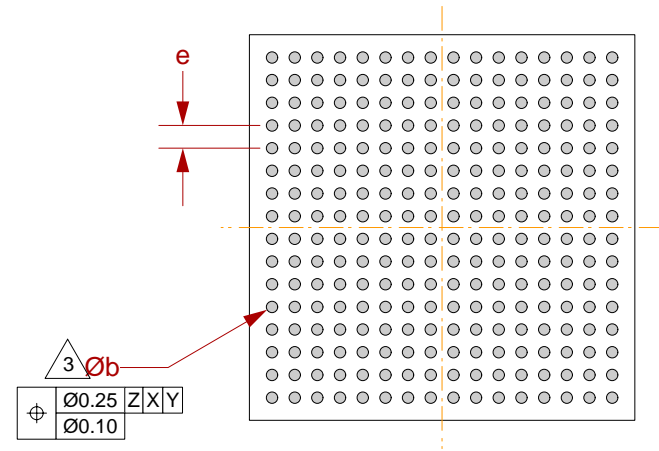
Compatible BGA Spec



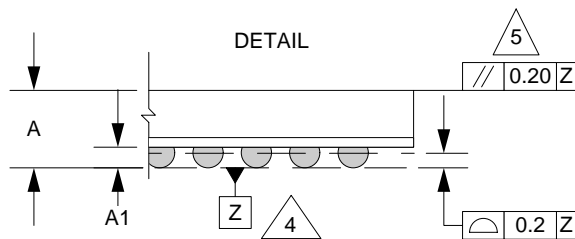
TOP VIEW



SIDE VIEW



BOTTOM VIEW



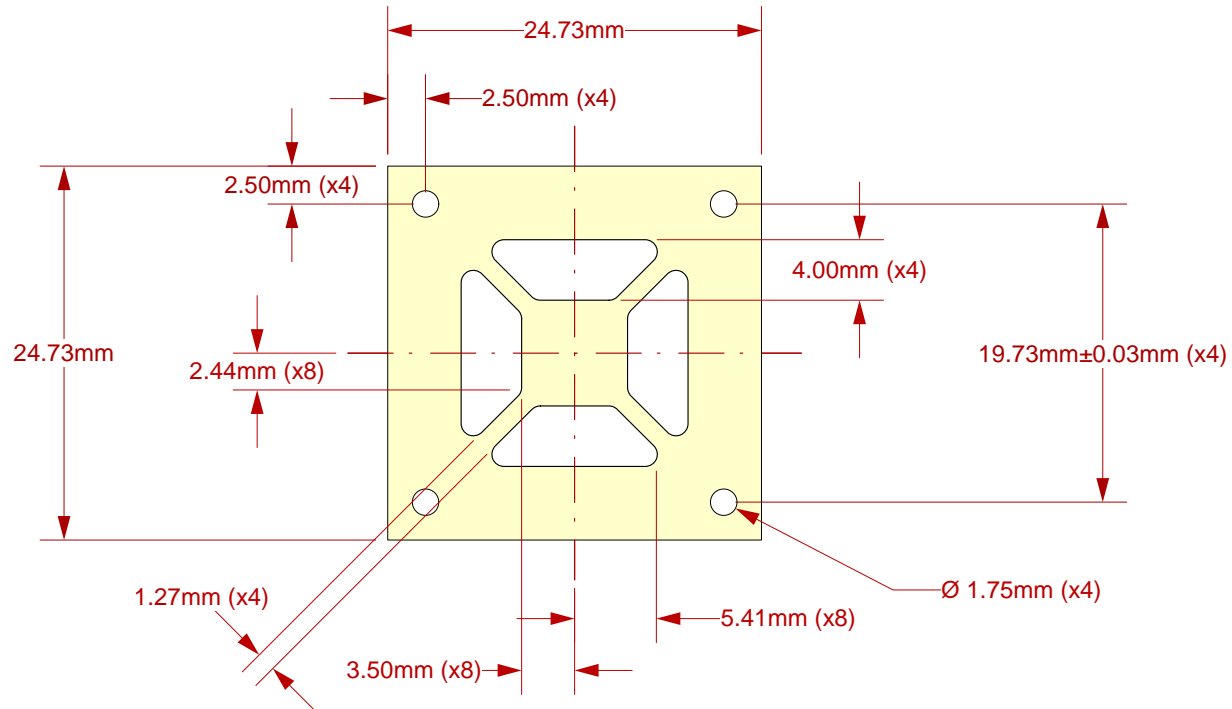
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.0
A1	0.3	0.5
b		0.5
D	17.00 BSC	
E	17.00 BSC	
e	1.0 BSC	

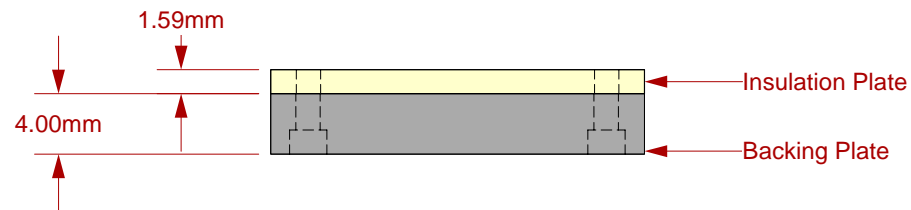
16 x 16 Array

	SS-BGA256E-01 Drawing	Status: Released	Scale:	Rev: C
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		File: SS-BGA256E-01 Dwg	Modified: 12/20/07	

Top View




Side View

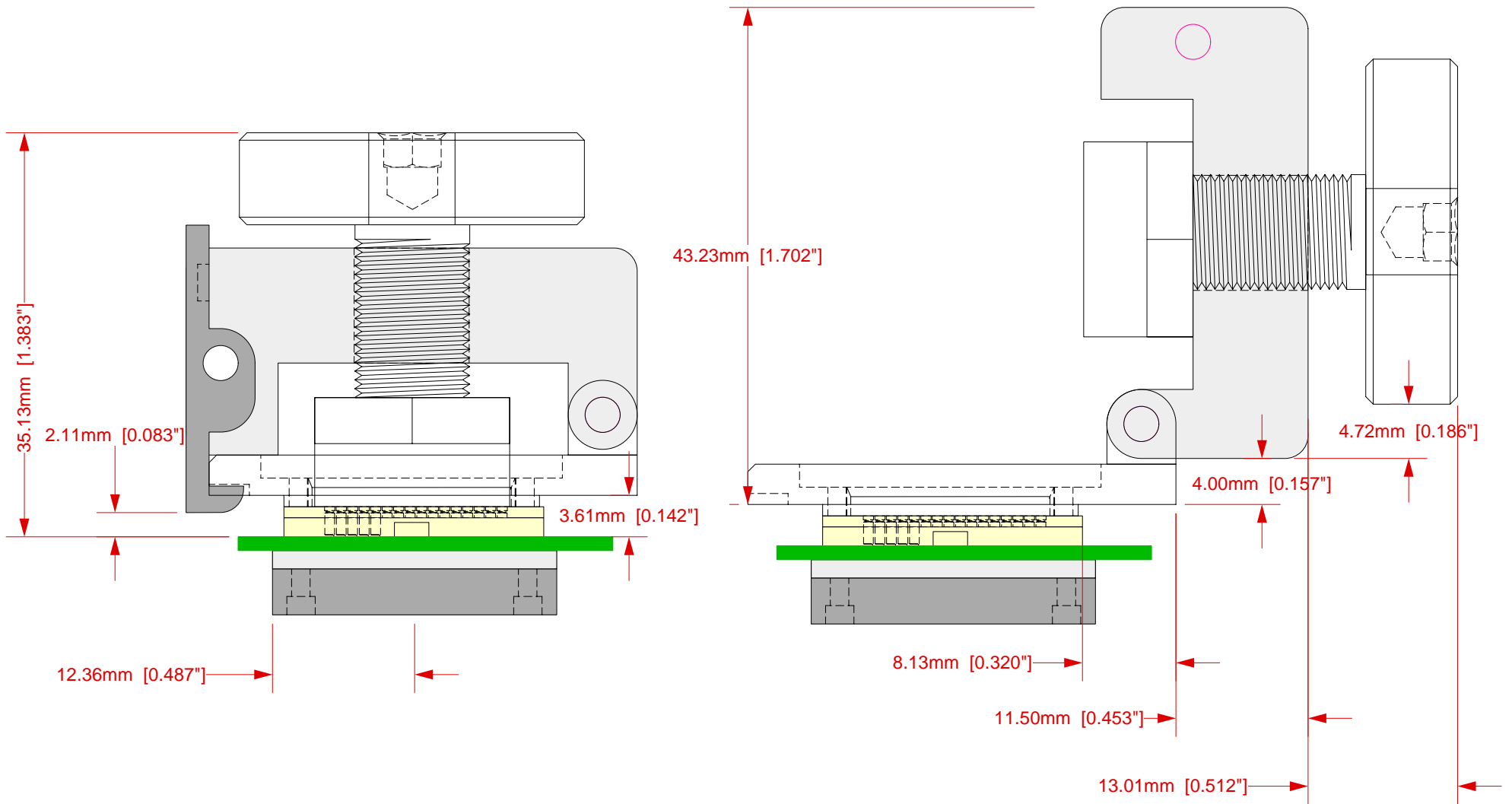



Description: Backing Plate with Insulation Plate

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		File: SS-BGA256E-01 Dwg	Modified: 12/20/07	

All dimensions are in mm.
 All tolerances are $\pm 0.125\text{mm}$.
 (Unless stated otherwise)



	SS-BGA256E-01 Drawing		Status: Released	Scale:	Rev: C
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			File: SS-BGA256E-01 Dwg		Modified: 12/20/07